



# M T B F

(E I A J R C R - 9 1 0 2 B)

Model	GT3.5-12
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No.	Parts		Q' ty of Device	Failure rate [ $10^{-6}/H$ ]	Reference
1	IC	Linear	2	0.0480	
2	Transistors	NPN/PNP	0	0.0000	
3	Transistors	Power NPN/PNP	1	0.0420	
4	FET	MOS FET	2	0.1980	
5	Diodes	FR	2	0.0440	
6	Diodes	Zener	2	0.0480	
7	Diodes	bridge	2	0.1320	
8	Resistors	Metal Film	23	0.3680	
9	Resistors	Power Film	3	0.1230	
10	Resistors	cement	4	0.1640	
11	Resistors	variable	1	0.0160	
12	Capacitors	Aluminum Electrolytic	10	0.1900	
13	Capacitors	Film	5	0.0420	
14	Transformer	Power	1	0.3600	
15	Fuses		1	0.0200	
16	Connectors	Printed Crcuit Board	7	0.3640	
17	Connection	Hand Solder	17	0.0442	
18	Connection	Flow Solder	307	0.1596	
19	Connection	Crimp	31	0.0192	
20	Connection	Screw	10	0.0100	
21	Printed Crcuit Board	Through Hole	4	0.1800	
Total Failure Rate [ $10^{-6}/H$ ]				2.5721	

M T B F	[H]	388,000
Ambient Temperature	[°C]	-
Load Factor	[%]	-